

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TSUNG JEN LIAO	03/29/2013
RECEIVING PARTY DATA	
Name:	CHIPMOS TECHNOLOGIES INC.
Street Address:	NO. 1, R&D RD. 1, SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13855264
CORRESPONDENCE DATA	
Fax Number:	9492503178
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	949 387 2885
Email:	JKuno@wpatca.com
Correspondent Name:	WPAT, PC INTELLECTUAL PROPERTY ATTORNEYS
Address Line 1:	1100 Quail Street, Suite 202
Address Line 4:	Newport Beach, CALIFORNIA 92660
ATTORNEY DOCKET NUMBER:	18506-598
NAME OF SUBMITTER:	Anthony King
Signature:	/Anthony King/
Date:	04/02/2013
Total Attachments: 2 source=Assign_18506-598#page1.tif source=Assign_18506-598#page2.tif	

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PATENT

ASSIGNMENT

WHEREAS, I(we), LIAO, TSUNG JEN, whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled

MANUFACTURING METHOD FOR MICRO BUMP STRUCTURE

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date herewith unless at least one of the following is checked:

- ☐ United States Design Patent was
☐ executed on:
☐ filed on: Serial No.:
☐ established by PCT International Patent Application No.: filed: designating the
United States of America
☐ issued on _____ as U.S. Patent No.: _____

WHEREAS, CHIPMOS TECHNOLOGIES INC. whose post office address is NO. 1, R&D RD. 1, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN, R.O.C. hereinafter referred to as Assignee, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

Assignor Name LIAO, TSUNG JEN	Address NO. 1, R&D RD. 1, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN, R.O.C.
Signature of Assignor Liao, Tsung Jen	Date of Signature 29 March, 2013
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)